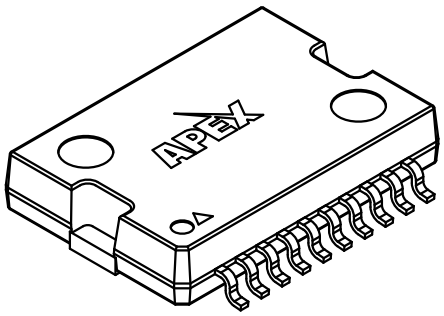
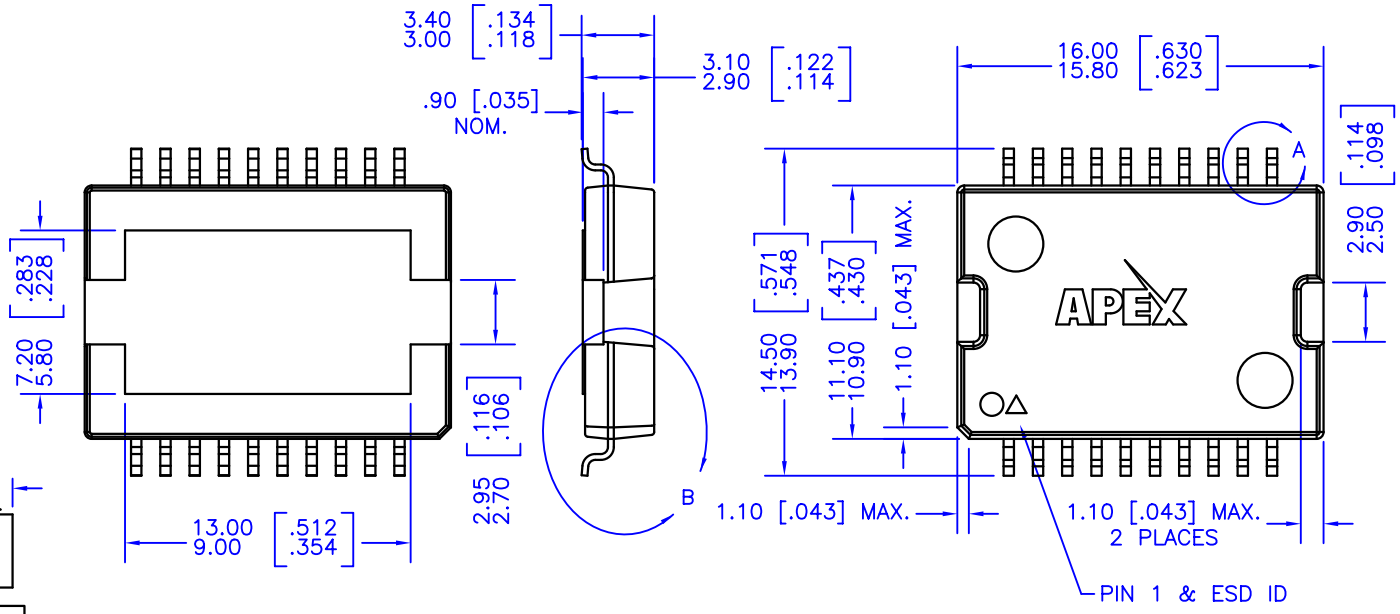
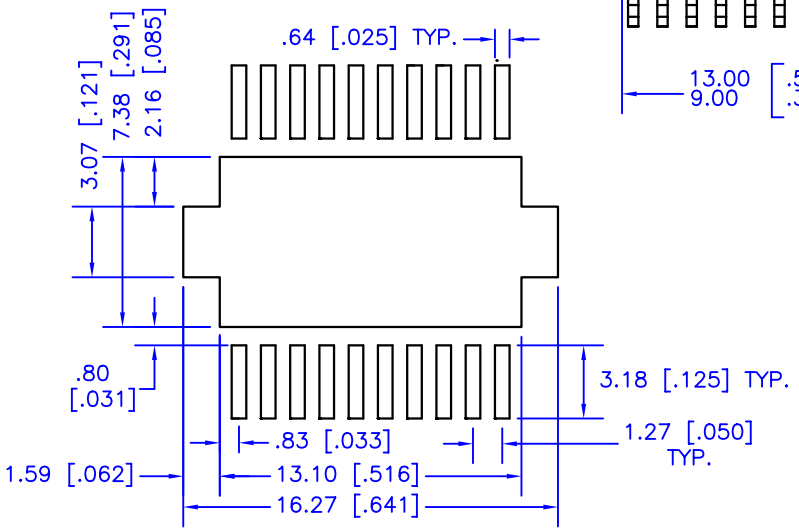
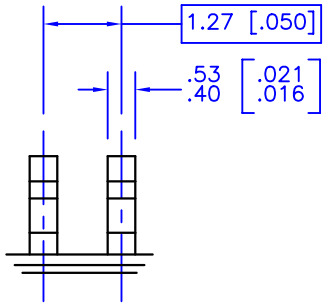


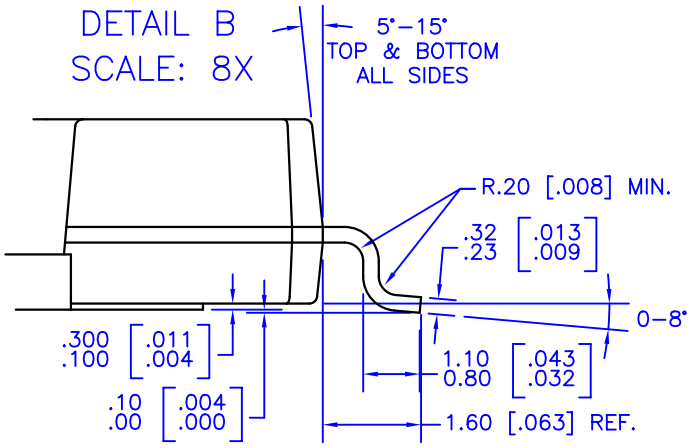




Surface Mount Layout



DETAIL A
SCALE: 8X



NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Heat Slug: C10200 copper with Ni–Pd–Au plating
5. Lead frame: C19400 copper with SNi–Pd–Au plating.
6. Mold compound: MP–8000AN or EME6600HR epoxy
7. Package weight: .086 oz. [2.44 g]
8. Suggested surface mount layout for reference only.

TOLERANCES – UNLESS OTHERWISE SPECIFIED								
.XX = ±.01 [.254]	APEX MICROTECHNOLOGY	TITLE: 20-PIN PSOP (JEDEC MO-166)					PACKAGE: DK	
.XXX = ±.005 [.127]		SUBJECT: MECHANICAL PACKAGE OUTLINE						
ANG. = ±.5°		ENG. D–M	TECH/DWN. P.ECK	DCA 90350	SH. 1 OF 1	FILENAME: DK	REV E	DATE 20AUG09